

WHAT IS CLAIMED IS:

1. A semiconductor device including a semiconductor substrate having a surface provided with an external connection electrode and a surface opposite that with said external connection electrode, abraded and reinforced with a back-surface reinforcement member.
2. The semiconductor device of claim 1, wherein said back-surface reinforcement member is formed of resin.
3. The semiconductor device of claim 2, wherein said resin is formed of a material having an elastic modulus of 1.5×10^6 N/m² to 5.0×10^6 N/m².
4. The semiconductor device of claim 2, wherein said resin is selected from the group consisting of resin of rubber type, resin of silicone type, resin of epoxy type, resin of polyimide type and resin of urethane type.
5. A method of manufacturing a semiconductor device comprising the steps of: abrasing a surface of a semiconductor substrate opposite to a surface thereof having an external connection electrode; and applying resin on said surface abraded.
6. The method of claim 5, further comprising the step of cutting said semiconductor substrate after the step of applying.
7. The method of claim 5, further comprising the step of previously grinding said surface to be abraded.
8. The method of claim 6, further comprising the step of previously grinding said surface to be abraded.
9. The method of claim 5, wherein in the step of applying, said

resin is printed.

10. The method of claim 6, wherein in the step of applying, said resin is printed.

11. The method of claim 7, wherein in the step of applying, said resin is printed.

12. The method of claim 8, wherein in the step of applying, said resin is printed.

13. The method of claim 5, wherein in the step of applying, said resin is applied by spin-coating.

14. The method of claim 6, wherein in the step of applying, said resin is applied by spin-coating.

15. The method of claim 7, wherein in the step of applying, said resin is applied by spin-coating.

16. The method of claim 8, wherein in the step of applying, said resin is applied by spin-coating.